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Part Number: [0736442017](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location A, Polarizing Key Position N/A, 72 Circuits, Mating Length 5.00mm

Documents:

3D Model	Test Summary TS-73670-990-001 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)
Packaging Specification PK-70873-0818 (PDF)	

Agency Certification

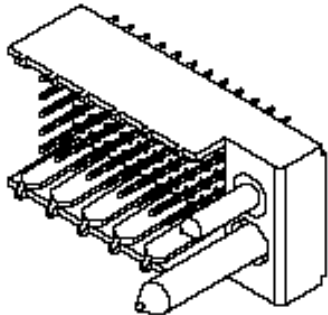
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73644
Application	Backplane
Comments	Standard Press-Fit, Tin/Lead (SnPb), Standard Press-Fit, Tin/Lead (SnPb)
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800753943308

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	None
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	5.615/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Not Reviewed

REACH SVHC

Contained Per -
ED/71/2019 (16 July
2019)

Lead

Halogen-Free

Status

Low-Halogen

For more information, please visit [Contact US](#)

China ROHS	50 Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

[73644](#) Series

Mates With

[73632](#) HDM+ Board-to-Board Daughtercard Receptacle. [73780](#) HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Signal	622008502
Insertion Module	
Press-In Tool for 2.00mm Pitch HDM*	

Termination Interface: Style	Through Hole - Compliant Pin	Board-to-Board Backplane Header
Electrical		
Current - Maximum per Contact	1.0A	
Data Rate	1.0 Gbps	
Real Signals (per 25mm)	75	
Shielded	No	
Voltage - Maximum	250V AC	
Solder Process Data		
Lead-freeProcess Capability	N/A	
Material Info		
Reference - Drawing Numbers		
Packaging Specification	PK-70873-0818	
Sales Drawing	SDA-73644-XXXX	
Test Summary	TS-73670-990-001	

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